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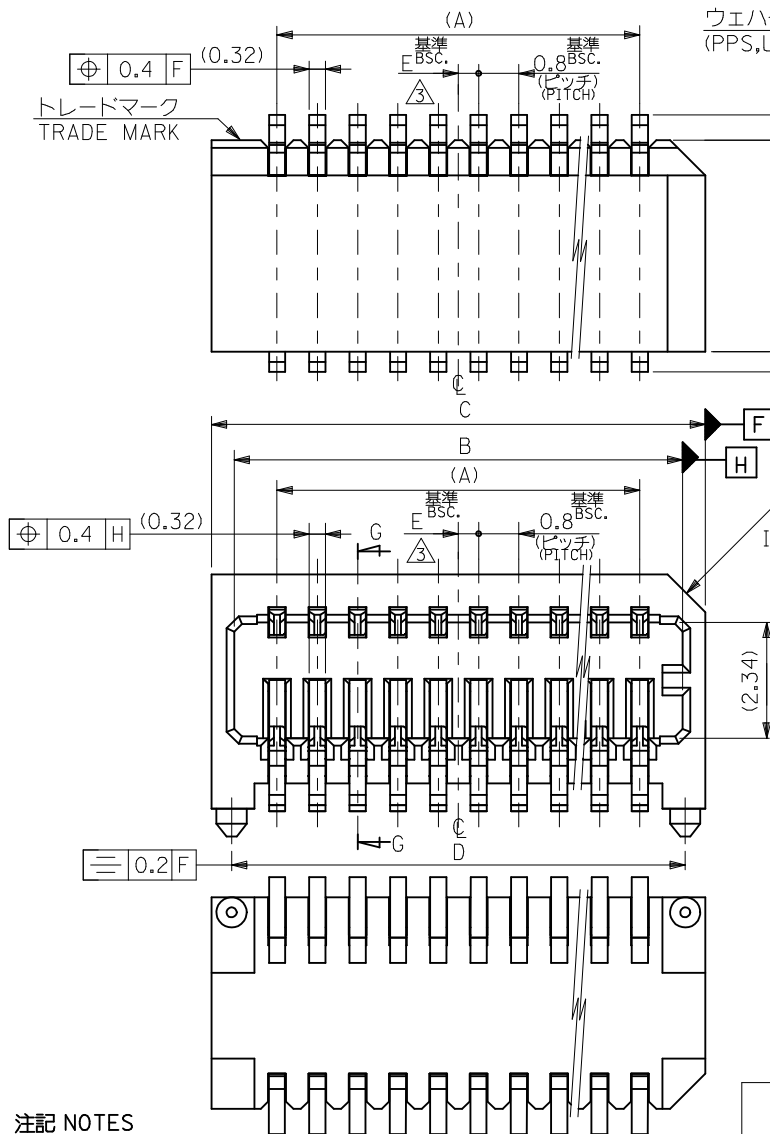
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ウェハー WAFER
(PPS,UL94V-0)

ピン PIN

(リン青銅、錫メッキ、ニッケルメッキ (下地)
t=0.32)
(PHOS-BRO. TIN-PLATED,
NICKEL-UNDER PLATING t=0.32)

コネクタ位置
CONNECTOR
POSITION

2-φ0.8
(位置決め用穴)
(LOCATING
HOLE)

回路番号1
(表示用切欠き)
CHAMFERING TO
INDICATE CKT. NO.1

SECT. G-G

基板端面
END OF P.C.B.

参考基板レイアウト (マウント面)
P.C.B. PATTERN LAYOUT (REF.) (MOUNT AREA)

0.4	17.0	17.8	16.9	15.2	53309-4019	40
0.8	16.2	17.0	16.1	14.4	-3819	38
0.4	15.4	16.2	15.3	13.6	-3619	36
0.8	14.6	15.4	14.5	12.8	-3419	34
0.4	13.8	14.6	13.7	12.0	-3219	32
0.8	13.0	13.8	12.9	11.2	-3019	30
0.4	12.2	13.0	12.1	10.4	-2819	28
0.8	11.4	12.2	11.3	9.6	-2619	26
0.4	10.6	11.4	10.5	8.8	-2419	24
0.8	9.8	10.6	9.7	8.0	-2219	22
0.4	9.0	9.8	8.9	7.2	-2019	20
0.8	8.2	9.0	8.1	6.4	-1819	18
0.4	7.4	8.2	7.3	5.6	-1619	16
0.8	6.6	7.4	6.5	4.8	-1419	14
0.4	5.8	6.6	5.7	4.0	-1219	12
0.8	5.0	5.8	4.9	3.2	53309-1019	10

注記 NOTES

1. 嵌合相手: 52465,52588シリーズ
MATE WITH : 52465,52588 SERIES
2. ウェハーの C から隣接するピンの C 迄の位置を示す。
SHOW POSITION FROM C OF WAFER TO C OF ADJACENT PINS.
3. 本製品は 53309-**17 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53309-**17.

REVISED EC NO: J2014-0465 DRWN:Y.TSUDA CHKD:TASAKAWA APPR:TASAKAWA 2013/09/12 2013/09/12 2013/09/13	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY HKAWABATA	DATE 2004/03/10	TITLE 0.8 B/B CONN SMT WITH BOSS -LEAD FREE-				
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTOJO	DATE 2004/03/10					
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2004/03/10	molex				
		ANGULAR ±3 °		MATERIAL NO.						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE DRAWING		SD-53309-013			1 OF 2		
A	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

9 8 7 6 5 4 3 2

10 9 8 7 6 5 4 3 2 1

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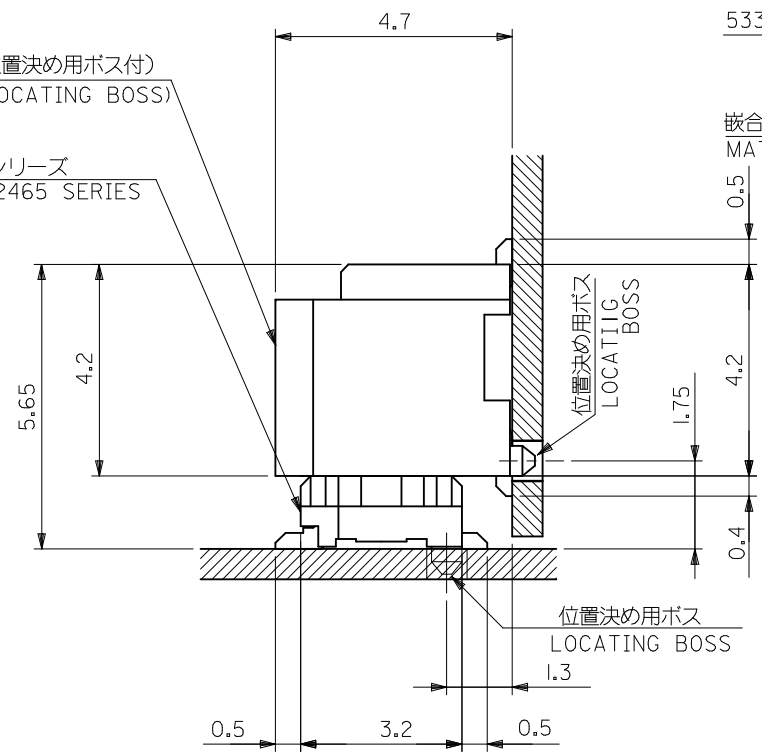
D D

C C

B B

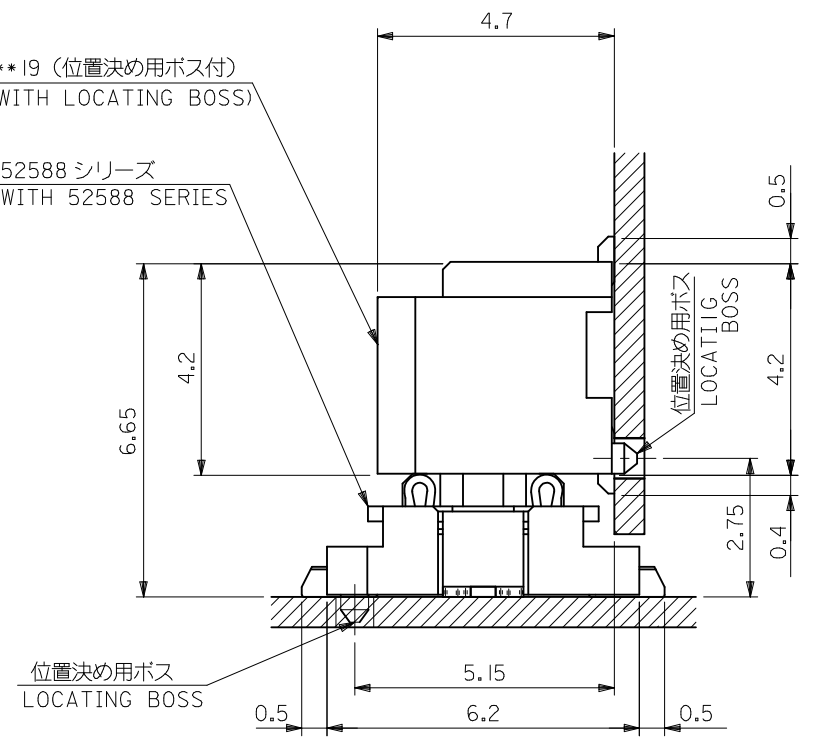
A A

53309-***19 (位置決め用ボス付)
(WITH LOCATING BOSS)
嵌合相手 52465 シリーズ
MATES WITH 52465 SERIES



嵌合状態図 (参考)
MATED DRAWING(REF.)

53309-***19 (位置決め用ボス付)
(WITH LOCATING BOSS)
嵌合相手 52588 シリーズ
MATES WITH 52588 SERIES



嵌合状態図 (参考)
MATED DRAWING(REF.)

9 8 7 6 5 4 3 2

REVISED EC NO: J2014-0465 DRWN:Y SHIDA 2013/09/13 CHKD:TASAKAWA 2013/09/13 APPR:TASAKAWA 2013/09/13 A	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		10 UNDER	±0.2	DRAWN BY HKAWABATA	DATE 2004/03/10	TITLE 0.8 B/B CONN SMT WITH BOSS -LEAD FREE-					
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 2004/03/10						
		30 OVER	±0.3	APPROVED BY MSASAO	DATE 2004/03/10	molex					
		ANGULAR ±3 °		MATERIAL NO.							DOCUMENT NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		REFER TO SHEET 1 OF 2		SD-53309-013				2 OF 2	
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

1. 梱包数量：1000個／リール NUMBER OF CONNECTORS:1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH

トップテープ TOP TAPE
リーダー部 LEADER PART
未接着部 NON-BONDED PART

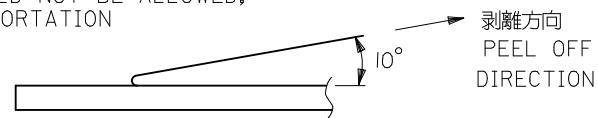
175 ±25 25 ±5

引き出し方向
PULL OUT
DIRECTION



3. トップテープの剥離強度：（剥離方向は下図参照）
0. 1～1. 3N {10～130gf} 尚、本規格値は、出荷時に適用。
（但し、輸送時に剥離が発生しない事。）
PEELING OFF FORCE OF TOP TAPE
0.1～1.3N {10～130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION

引き出し方向
PULL OUT
DIRECTION



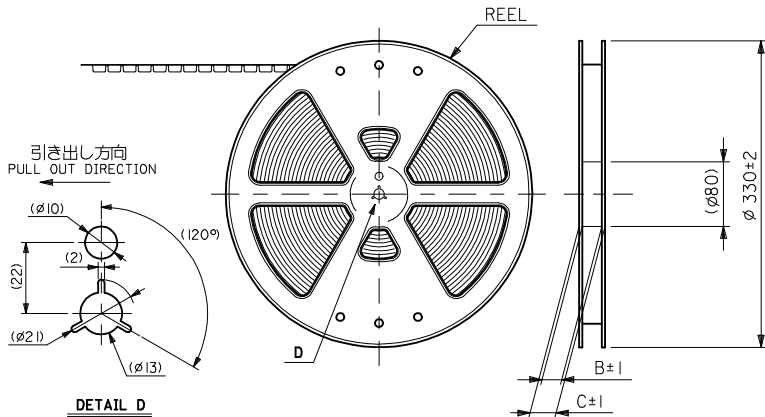
5. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリプロピレン(POLYPROPYLENE)
トップテープ(TOPTAPE)：PET , PE , PEF
リール (REEL)：ポリスチレン (PS) <リサイクル材を含む>
POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>
6. 本製品は53309-**-90の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53309-**-90.

16	21.4	17.4	9.3	53309-1871	18
			8.5	53309-1671	16
			7.7	53309-1471	14
			6.9	53309-1271	12
			6.1	53309-1071	10
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT

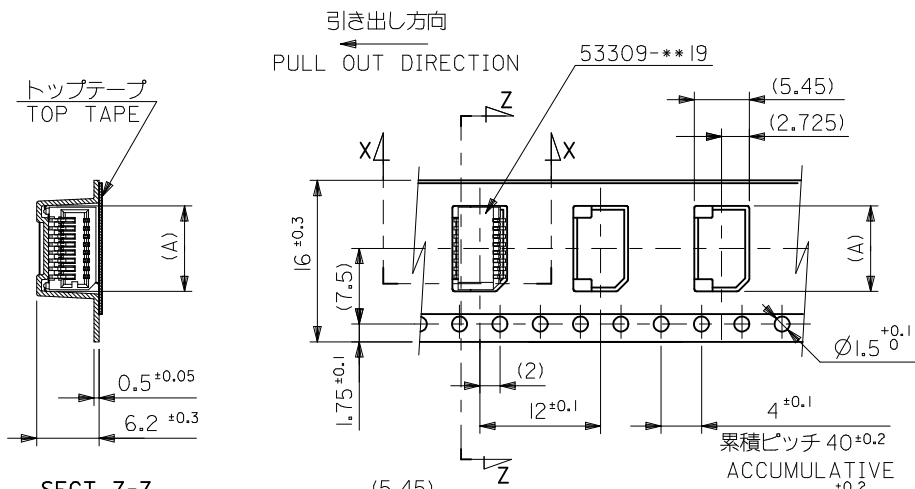
DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
DRAWN BY ABATA	DATE 2004/03/10	TITLE 0.8 BTB CONN WAFER ASSY EMBSTP PKG -LEAD FREE-			
CHECKED BY JO	DATE 2004/03/10				
APPROVED BY AO	DATE 2004/03/10				
MATERIAL NO.		DOCUMENT NO.			SHEET NO.
SEE NOTES		SD-53309-014			1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

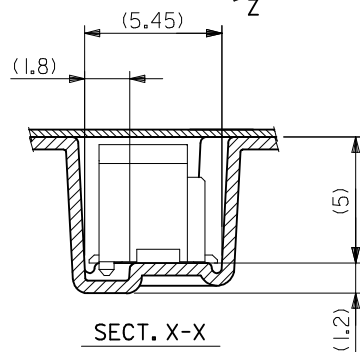
注記 NOTES



DETAIL D



SECT. Z-Z



SECT. X-X

REVISED EC NO: J2014-0465 2013/09/13 DRWN:Y SHIDA 2013/09/13 CHKD:TASAKAWA 2013/09/13 APPR:TASAKAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	
		10 UNDER	±0.2
		10 OVER 30 UNDER	±0.25
		30 OVER	±0.3
		ANGULAR	±3 °
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	
A	REV		

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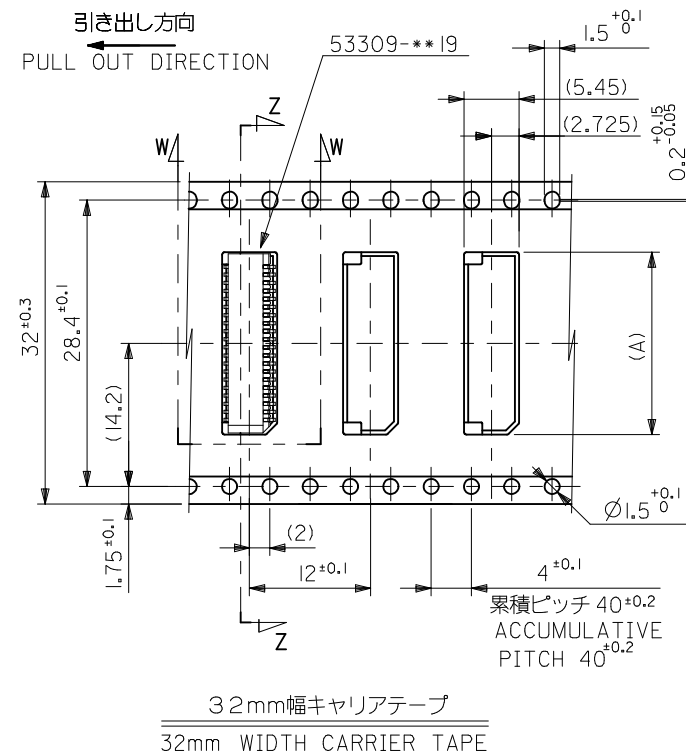
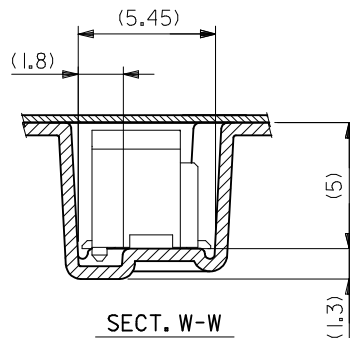
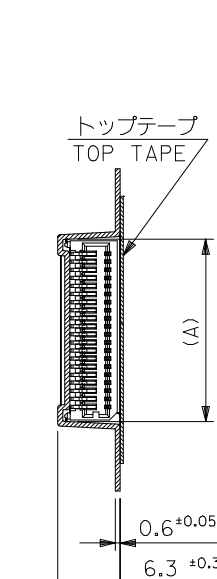
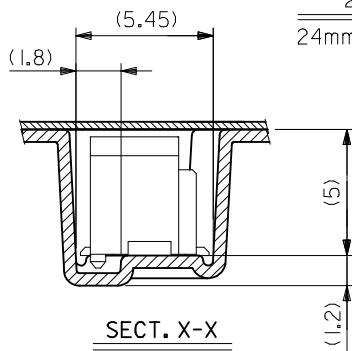
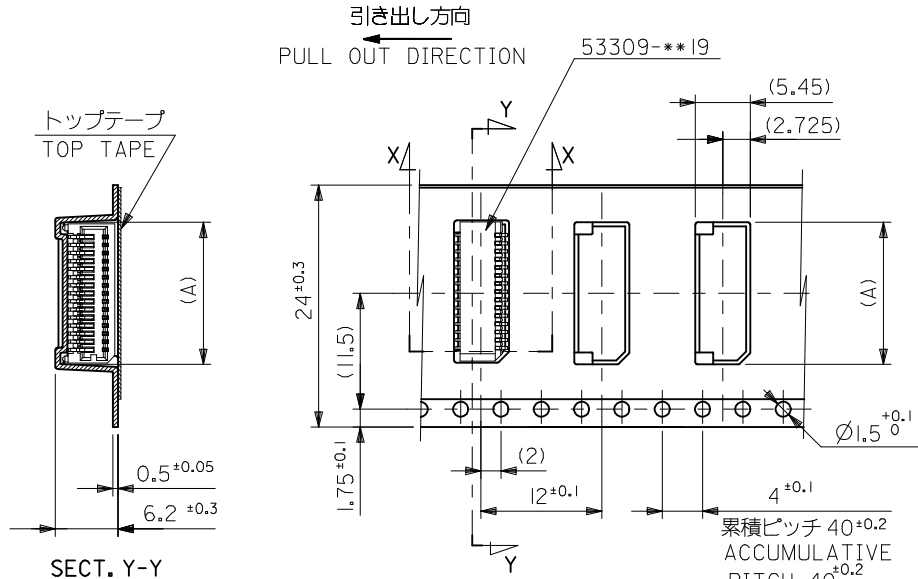
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24	29.4	25.4	16.5	53309-3671	36
			15.7	53309-3471	34
			14.9	53309-3271	32
			14.1	53309-3071	30
			13.3	53309-2871	28
			12.5	53309-2671	26
			11.7	53309-2471	24
			10.9	53309-2271	22
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	10.1	53309-2071	20
			(A)	MATERIAL NO.	極数 CIRCUIT

REVISED
EC NO: J2014-0465
2013/09/13
DRWN: Y. ISHIDA
CHKD: TASAKAWA
APPR: TASAKAWA
2013/09/13

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3°
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

53309-**-71
MODEL NO.

32		37.4	33.4	18.1 17.3	53309-4071 53309-3871	40 38
キャリアテープ幅 CARRIER TAPE WIDTH		C	B	(A)	MATERIAL NO.	極数 CIRCUIT
DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
DRAWN BY AWABATA		DATE 2004/03/10		TITLE 0.8 BTB CONN WAFER ASSY EMBSTP PKG -LEAD FREE- molex		
CHECKED BY OJO		DATE 2004/03/10				
APPROVED BY ASAO		DATE 2004/03/10				
SERIAL NO.		DOCUMENT NO.				SHEET NO.
REFER TO SHEET 1 OF 2		SD-53309-014				2 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						